

Package Material Composition and Mass Calculation

Customer: PLX
 Package: QFP 160L (28 X 28)
 Device Type: PCI9052 G
 Pad/Cavity Size: 354 SQ MILS
 Die Size: 188 X 175 MILS

Date: 14/09/2004

	name	composition	%	mg.(ave)	density	mg.	%	PPM
Mold Compound	Sumitomo G600C					<u>4447.8</u>	<u>86.72</u>	<u>867,237</u>
		Silica Fused	75~95	3113.46			60.71	607,066
		Epoxy Resin	2-8	1111.95			21.68	216,809
		Cresol Novolac	1-3	75.613			1.47	14,743
		Phenol Resin	2-8	111.195			2.17	21,681
		Carbon Black	0.1-0.5	35.5824			0.69	6,938
Leadframe	C7025				<u>3.32</u>	<u>608.4</u>	<u>11.86</u>	<u>118,627</u>
		Composition						
		Cu	96.20	585.28			11.41	114,119
		Ni	3.00	18.25			0.36	3,559
		Si	0.65	3.95			0.08	771
		Mg	0.15	0.91			0.02	178
Die	Silicon	Silicon			2.4	<u>19.4</u>	<u>0.38</u>	<u>3,783</u>
Die Attach	Ablebond 8361J					<u>2.8</u>	<u>0.05</u>	<u>546</u>
		gamma-Butyrolactone	1~10	0.17			0.00	33
		Silver	70~80	2.10			0.04	409
		Epoxy Resin	1~10	0.17			0.00	33
		Diglycidylether of bisphenol-F	5~15	0.36			0.01	71
Wire					<u>19.3</u>	<u>8.9</u>	<u>0.173533</u>	<u>1,735</u>
		Au	99.99	8.8991			0.173516	1,735
		Ion Impurities	0.01	0.0009			1.73533E-05	0.174
External Plating	Solder Plate					<u>41.40</u>	<u>0.8072</u>	<u>8,072</u>
		Sn	100	41.4	7.9		0.8072	8,072
Total						<u>5128.7</u>	<u>100.00</u>	<u>1,000,000</u>